### MATRIX : VERS DE L'IMAGERIE PROTONS



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# MATRIX : GaN diode array for proton monitoring and imaging

#### ANR

- CRHEA, Nice : GaN design
- CAL, Nice : test facility, MEDICYC proton line, 65 MeV, Proteus One, 230 MeV
- Ruhr-University, Bochum : GaN tests
- West German Proton Therapy Center, Essen : test facility, 230 MeV
- $\rightarrow$  IPHC, Strasbourg (from the detector to the signal)



Roadmap :

- GaN diode selection / process
- Laser / proton beam tests → selection (yield) ▲
- DAQ (cots if possible) 🚄
- Linear array of 64 diodes 🚄
- Proton beam tests 🚄
- Matrix (11x11) diodes
- MATRIX (128 x 128)
- Applications

2-D imaging array
36 cm<sup>2</sup> (500 μm<sup>2</sup> diode)
128 x 128 diodes
Current integration from the chip



# Why GaN?

	Bandgap (eV)	Breakdown field (MV/cm)	Electron mobility (cm <sup>2</sup> /Vs)	Thermal conductivity (W/mK)	Radiation hardness	Large area (industry)	Cost
SiC	2.36-3.23	3.5	900	320	+	+	-
GaN	3.4	3.4	1500	1300	+	+	-
Si	1.1	10	3000	230	-	+	
Diamond	5.47	0.3	1500	2130	+	-	+

#### INVESTIGATING DIODES STRUCTURES (500 µm<sup>2</sup> diode)

courtesy of M. Siviero (CRHEA)



### INVESTIGATING DIODES STRUCTURES cont'd

Substrate: no effect observed on the dark current nor the response to protons Sapphire substrates needed for medium and large size arrays  $\rightarrow$  3" wafers  $\Rightarrow$  Sapphire substrate

courtesy of J-Y. Duboz (CRHEA)

CC1605D Schottky 4 µm

-0 -0,2 -0,4

5.00E-08

0,00E+00

-5,00E-08

-1.00E-07

UV laser

Pin shows :

- higher responses
- lower dark current
- less response instability
- higher process yield than Schottky diodes
   ⇒ pin diodes

Thickness of undoped active region :

- Schottky: no clear trend among samples with L=1-2-4-10µm
- pin: samples with L=1-2-4-10µm.

Similar results for 2 and 10µm. 4µm to be measured

10µm very difficult to process

 $\Rightarrow$  Thickness will be in the range 1-2µm: processing yield is a key issue for arrays

#### **ACQUISITION SYSTEM**

#### COTS (Market survey)

- N channels (~128)
- Current input (up to 1ms), low noise
- → Xray imaging (radiotherapy)
  - Analog devices (in progress)
  - AMS-OSRAM (NDA)
    - AS5900 26 bit 128 Channel Low Noise Current-to-Digital

![](_page_5_Picture_8.jpeg)

![](_page_5_Picture_9.jpeg)

Closed software : biaising, etc.

![](_page_5_Figure_11.jpeg)

![](_page_5_Picture_12.jpeg)

14 channels :

- average of 10000 tests, 10s
- 1ms integration time
- 9 pin diodes 1606D0
- 5 Schottky diodes 1517A2
- Mean of mean : 422 pA 😳
- Std : 350 fA

2 dead channels

![](_page_5_Picture_21.jpeg)

#### **EVOLUTION OF THE SETUP**

![](_page_6_Picture_1.jpeg)

![](_page_6_Picture_2.jpeg)

#### CYRCE EXPERIMENT

- Proton beam with a frequency of 85 MHz or half <u>42 MHz</u>
- fA to 100 nA (25pA 10nA, our experiment)
- Beam Modulated On/Off with 1 s pulse duration
- Option to use a diffuser in proton beam line (makes beam more homogenous)
- Diodes read out by AMS Test Kit
- 1D line array of 64 diodes
- Stage allows 2D imaging

![](_page_7_Picture_8.jpeg)

![](_page_7_Picture_9.jpeg)

![](_page_7_Picture_10.jpeg)

## Diode response : time structure

![](_page_8_Figure_1.jpeg)

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# Normalizing the response (@5 nA) and the response (%5 nA) and the respo

courtesy of N. Broda (RUB)

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![](_page_9_Figure_2.jpeg)

# Signal and noise for different diode structures (e1, e2, d2)

![](_page_10_Figure_1.jpeg)

#### SENSITIVITY CC2121 pin diode 1µm nid GaN

AMS :

Min detect. proton current density :  $3 \text{ pA} / \text{cm}^2$ Min detect. proton current in the diode : 7.5 fA

Nb: 1.6 fA = 10000 protons / s

![](_page_10_Picture_6.jpeg)

# Proton beam imaging

![](_page_11_Figure_1.jpeg)

Empty round collimator imaging

![](_page_11_Picture_3.jpeg)

![](_page_11_Picture_4.jpeg)

# Imaging – real Image vs interpolated

#### courtesy of N. Broda (RUB)

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![](_page_12_Figure_2.jpeg)

# A (turn of the) screw

![](_page_13_Picture_1.jpeg)

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# Beam image without diffuser (Al, 40 µm)

![](_page_14_Figure_1.jpeg)

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### Beam structure 2<sub>8</sub> days later

![](_page_15_Figure_1.jpeg)

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# Application 1 : Beam energy monitoring ③

![](_page_16_Figure_1.jpeg)

50

60

Bragg peak

40

#measure 10

#measure 20

#measure 30

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### Application 2 : Radiolysis of Biomolecules (Radiochem, IPHC)

courtesy of Q. Raffy (IPHC, Strasbourg)

![](_page_17_Figure_2.jpeg)

# Application 3 : Beam monitoring (IBA)

Industrial irradiation facilities AERIAL (labcom, iphc) Aerial → High energy E-beam and X-rays (feerix) x-ray beamline (5 MeV, 7 MeV) electron beamline (10 MeV, maximum power 10 KW)

![](_page_18_Picture_2.jpeg)

CAL, Nice
 WPE ?
 < 100 µs</li>

temporal resolution measurement of the proton beam (one diode is enough)

feerix

![](_page_18_Picture_5.jpeg)

# Outlook

- More measurements in proton beam (CAL, WPE)
  - Physics simulations
  - IBA system comparison (ionisation chambers, 1mm res.), pencil beam
- Hadrontherapy (SiC), CNAO (500 MeV)
- Optical setup for diode excitation (laser)
  - Easier studying of AMS circuit parameters (fine tuning), capacitance, ...
- Further process of data analysis (relation to image processing)
- 2D array (11 x 11) and (k x 128) multiplexed
- Analog device testing

![](_page_19_Picture_10.jpeg)

# **TEAM EFFORT**

IPHC, Strasbourg L. The-Duc C. Wabnitz N. Arbor S. Higueret

RUB, Bochum A. Wieck N. Broda

WPE, Essen C. Bäumer L. Parschat

CAL, Nice J. Hérault P. Hofverberg M. Vidal

CRHEA, Nice J-Y. Duboz M. Siviero M. Hugues L. Lesourd

![](_page_20_Picture_6.jpeg)

![](_page_20_Picture_7.jpeg)

![](_page_20_Figure_8.jpeg)

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![](_page_21_Picture_0.jpeg)

![](_page_22_Picture_0.jpeg)

![](_page_22_Picture_1.jpeg)

#### Mask – single diode plan view

diode to have a 500µm period 490 µm 430 µm 230 µm N contact Ti Al 10µm (negative resist) N-GaN 10µm 90 µm Mesa nid GaN 10µm (positive resist) <mark>450 µm</mark> P contact Ni Au (negative resist) Opening isolant 10µm (negative resist) Gold wire width=10µm length= 2cm

Distanced 10µm from the next

**IATRIX** 

### Mask – single diode side view

![](_page_24_Figure_1.jpeg)

![](_page_24_Picture_2.jpeg)